

PHOTOCOUPLER

PS2802-1,PS2802-4

HIGH ISOLATION VOLTAGE DARLINGTON TRANSISTOR TYPE SSOP PHOTOCOUPLER

-NEPOC Series-

DESCRIPTION

The PS2802-1 and PS2802-4 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon darlington-connected photo transistor in a plastic SSOP for high density applications.

This package has shield effect to cut off ambient light.

FEATURES

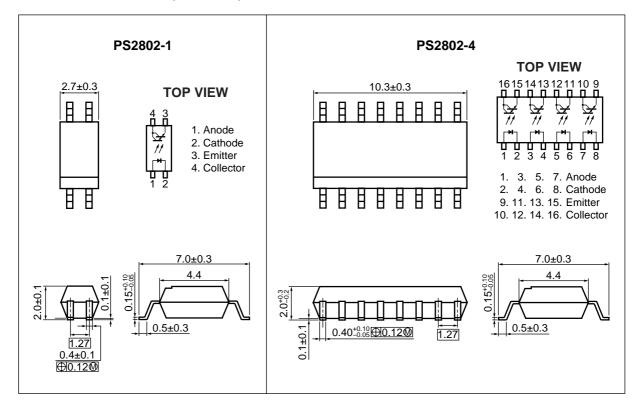
- High isolation voltage (BV = 2 500 Vr.m.s.)
- Small and thin package (4,16-pin SSOP, Pin pitch 1.27 mm)
- High current transfer ratio (CTR = 2 000% TYP. @ # = 1 mA, VcE = 2 V)
- Ordering number of tape product: PS2802-1-F3, F4, PS2802-4-F3, F4
- ★ Safety standards: PS2802-1, -4
 - UL approved: File No. E72422
 - BSI approved: No. 8188, 8189
 - CSA approved: File No. CA 101391
 - DIN EN60747-5-2 (VDE0884 Part2) approved (Option)

APPLICATIONS

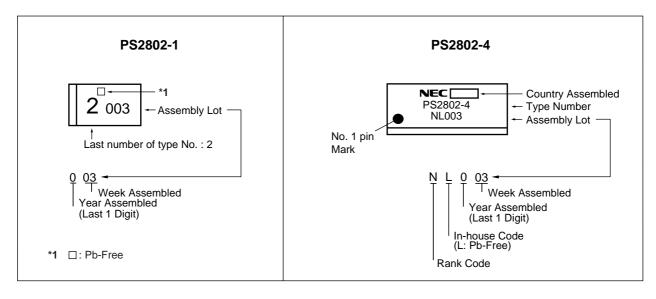
- · Programmable logic controllers
- Measuring instruments
- Hybrid IC

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PACKAGE DIMENSIONS (UNIT: mm)



★ MARKING EXAMPLE



★ ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number *1
PS2802-1	PS2802-1-A	Pb-Free	50 pcs (Tape 50 pcs cut)	Standard products	PS2802-1
PS2802-1-F3	PS2802-1-F3-A		Embossed Tape 3 500 pcs/reel	(UL, BSI, CSA	
PS2802-1-F4	PS2802-1-F4-A			approved)	
PS2802-1-V	PS2802-1-V-A		50 pcs (Tape 50 pcs cut)	DIN EN60747-5-2	
PS2802-1-V-F3	PS2802-1-V-F3-A		Embossed Tape 3 500 pcs/reel	(VDE0884 Part2)	
PS2802-1-V-F4	PS2802-1-V-F4-A			Approved (Option)	
PS2802-4	PS2802-4-A		Magazine Case 45 pcs	Standard products	PS2802-4
PS2802-4-F3	PS2802-4-F3-A		Embossed Tape 2 500 pcs/reel	(UL, BSI, CSA	
PS2802-4-F4	PS2802-4-F4-A			approved)	
PS2802-4-V	PS2802-4-V-A		Magazine Case 45 pcs	DIN EN60747-5-2	
PS2802-4-V-F3	PS2802-4-V-F3-A		Embossed Tape 2 500 pcs/reel	(VDE0884 Part2)	
PS2802-4-V-F4	PS2802-4-V-F4-A			Approved (Option)	

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25℃, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS2802-1	PS2802-4	
Diode	Forward Current (DC)	lf	50		mA/ch
	Reverse Voltage	VR	6		V
	Power Dissipation Derating	⊿P₀/°C	0.6	0.8	mW/°C
	Power Dissipation	PD	60	80	mW/ch
	Peak Forward Current *1 IFP 1		1	A/ch	
Transistor	Collector to Emitter Voltage	Vceo	40		V
	Emitter to Collector Voltage	Veco	6		V
	Collector Current	Ic	90	100	mA/ch
	Power Dissipation Derating	⊿Pc/°C	1.2		mW/°C
	Power Dissipation	Pc	120		mW/ch
Isolation Voltage *2		BV	2 500		Vr.m.s.
Operating Ambient Temperature		TA	-55 to +100		°C
Storage Temperature		Tstg	-55 to +150		°C

^{*1} PW = 100 μ s, Duty Cycle = 1%

^{*2} AC voltage for 1 minute at $T_A = 25$ °C, RH = 60% between input and output Pins 1-2 shorted together, 3-4 shorted together (PS2802-1).

Pins 1-8 shorted together, 9-16 shorted together (PS2802-4).

ELECTRICAL CHARACTERISTICS (TA = 25 °C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	I _F = 5 mA		1.1	1.4	V
	Reverse Current	lR	V _R = 5 V			5	μА
	Terminal Capacitance	Ct	V = 0 V, f = 1.0 MHz		15		pF
Transistor	Collector to Emitter Dark Current	ICEO	Vce = 40 V, I _F = 0 mA			400	nA
Coupled	Current Transfer Ratio (Ic/ıғ) *1	CTR	IF = 1 mA, VcE = 2 V	200	2 000		%
	Collector Saturation Voltage	VCE(sat)	I _F = 1 mA, I _C = 2 mA			1.0	V
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1.0 MHz		0.4		pF
	Rise Time *2	t r	$Vcc = 5 \text{ V, } Ic = 2 \text{ mA, } RL = 100 \Omega$		200		μS
	Fall Time *2	t f			200		

*1 CTR rank (PS2802-1 only)

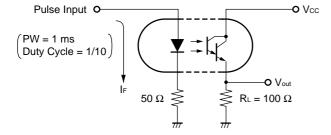
K: 2 000 to (%)

L: 700 to 3 400 (%)

M: 200 to 1 000 (%)

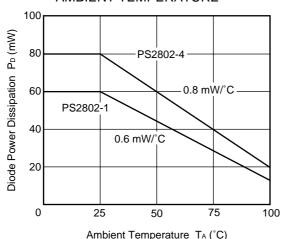
N: 200 to (%)

*2 Test circuit for switching time

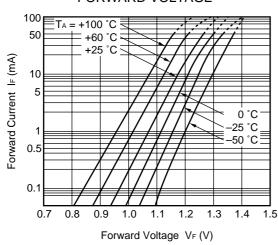


TYPICAL CHARACTERISTICS (T_A = 25℃, unless otherwise specified)

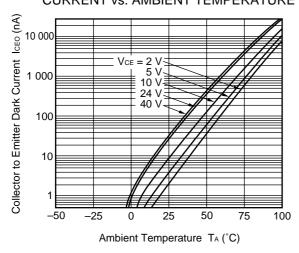




FORWARD CURRENT vs. FORWARD VOLTAGE

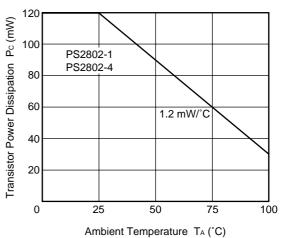


COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE

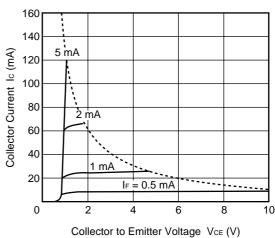


Remark The graphs indicate nominal characteristics.

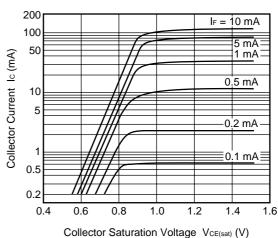
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



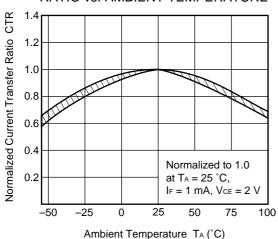
COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE



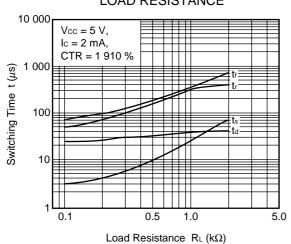
COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE



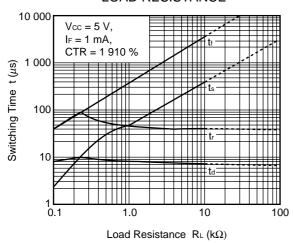
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



SWITCHING TIME vs. LOAD RESISTANCE

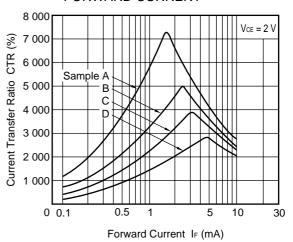


SWITCHING TIME vs. LOAD RESISTANCE

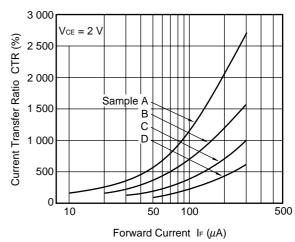


Remark The graphs indicate nominal characteristics.

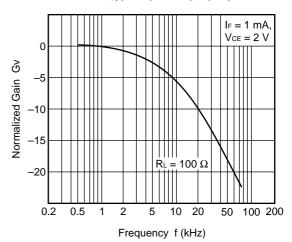
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



CURRENT TRANSFER RATIO vs. FORWARD CURRENT



FREQUENCY RESPONSE



LONG TERM CTR DEGRADATION 1.2 1.0 $I_F = 1 \text{ mA}$ $I_A = 25 \text{ °C}$ 0.6 0.6 0.7 0.2

Remark The graph indicates nominal characteristics.

Time (Hr)

10⁵

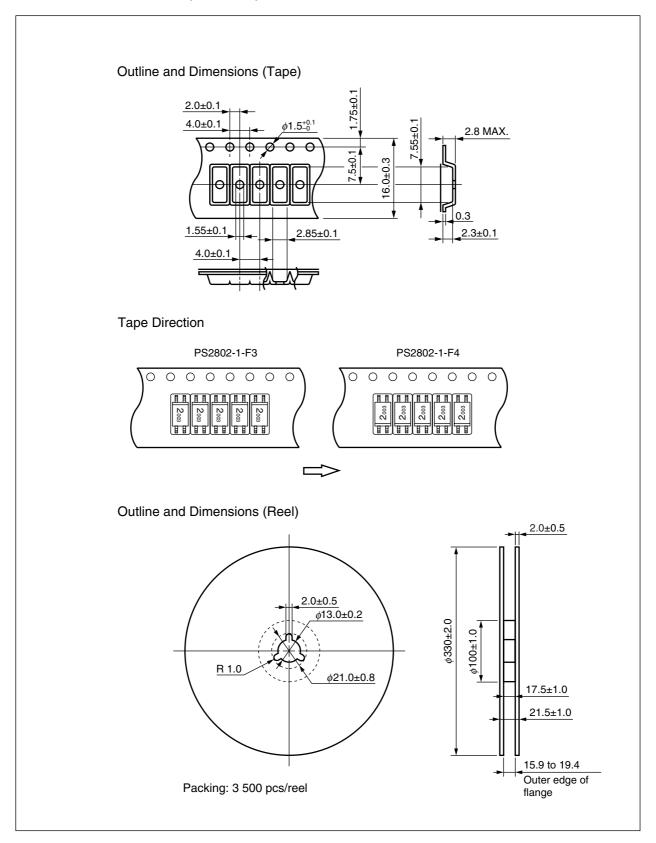
10⁶

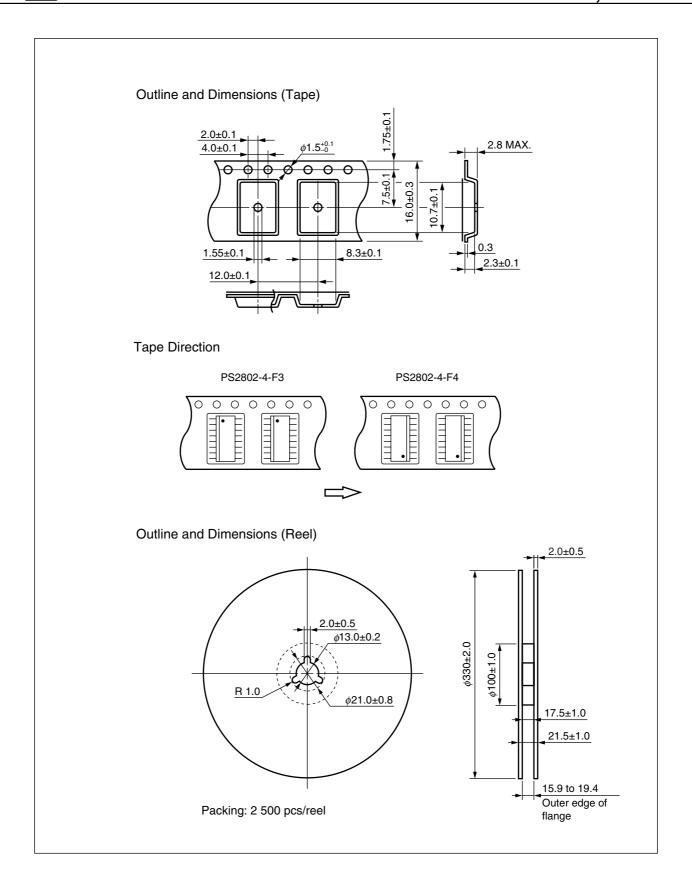
10³

0.0 10

10²

TAPING SPECIFICATIONS (UNIT: mm)





NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

· Peak reflow temperature 260C or below (package surface temperature)

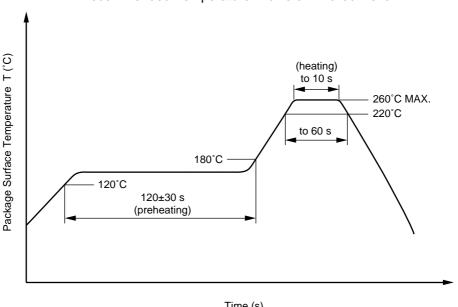
• Time of peak reflow temperature 10 seconds or less • Time of temperature higher than 220C 60 seconds or less

• Time to preheat temperature from 120 to 180C 120±30 s · Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

 Temperature 260C or below (molten solder temperature)

10 seconds or less Time

· Preheating conditions 120°C or below (package surface temperature)

· Number of times One (Allowed to be dipped in solder including plastic mold portion.)

• Flux Rosin flux containing small amount ofchlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

• Peak temperature (\(\)ead part temperature) 350°C or below · Time (each pins) 3 seconds or less

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

★ 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

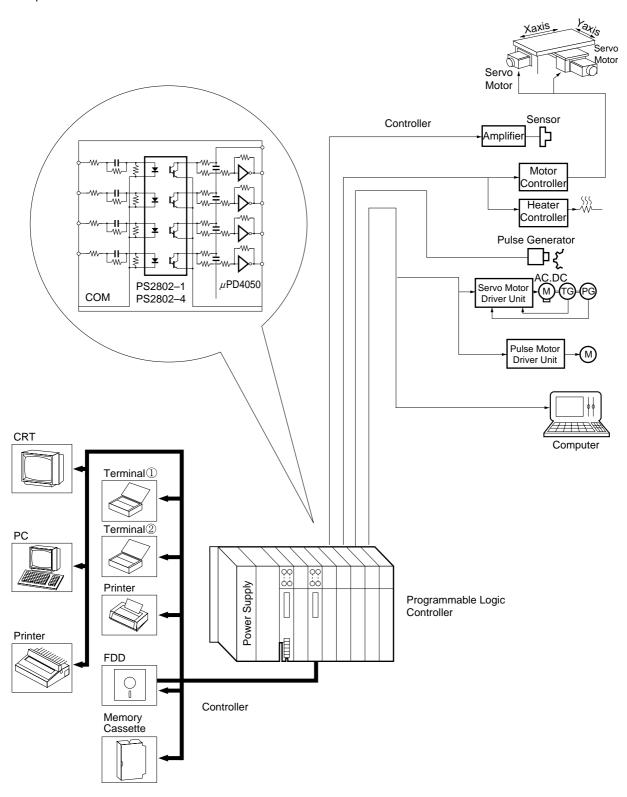
When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

PROGRAMMABLE LOGIC CONTROLLERS EXAMPLE

Purpose: In-out interface



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M8E 00.4-0110

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush,or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

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